

### **Amendments to the Claims**

Please amend Claims 1 and 6 and cancel Claims 7-12 as set forth below.

This listing of claims will replace all prior versions and listing of claims in the application.

### **List of Claims**

1. (amended) A method for interconnecting a plurality of electronic assemblies to form a cornerbond assembly comprised of:

providing a first electronic assembly with a first surface, said first surface including a conductive pattern thereon, said conductive pattern including a first terminal edge,

providing a second electronic assembly with a second surface, said second surface including a conductive pattern thereon, said conductive pattern including a second terminal edge,

orienting said first electronic assembly with respect to said second electronic assembly whereby said first surface is angularly disposed to said second surface and said first terminal edge and said second terminal edge are substantially registered to form a junction,

fixedly applying at least one ~~conductive~~ wire ball to said junction whereby said first conductive pattern is electrically interconnected to said second conductive pattern.

2. (original) The method of claim 1 wherein said first electronic assembly includes a three dimensional, multi-layer electronic module and said second electronic assembly includes a printed circuit board.
3. (original) The method of claim 1 wherein said first surface and said second surface are angularly disposed at an angle of about 90 degrees.
4. (original) The method of claim 1 wherein said first surface and said second surface are angularly disposed at an angle greater than 90 degrees.
5. (original) The method of claim 1 wherein said first surface and said second surface are angularly disposed at an angle less than 90 degrees.
6. (amended) The method of claim 1 further comprising the step of encapsulating said junction after said at least one ~~conductive~~ wire ball has been fixedly applied.

Claims 7-12 (cancelled).